N-Channel 100-V (D-S) MOSFET

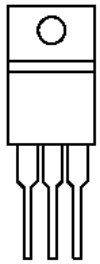
These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers.

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ m(Ω)	I_D (A)
100	16 @ V_{GS} = 10V	87[a]
	19 @ V_{GS} = 5.5V	

- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe TO-220CFM saves board space
- Fast switching speed
- High performance trench technology

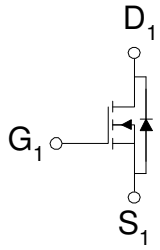
Pb-free
RoHS COMPLIANT
HALOGEN FREE

TO-220CFM



G D S

Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Limit	Units
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current[a]	T_C=25°C	I_D	87	A
Pulsed Drain Current[b]		I_{DM}	240	
Continuous Source Current (Diode Conduction)[a]		I_S	90	A
Power Dissipation[a]	T_C=25°C	P_D	300	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient[a]	$R_{\theta JA}$	62.5	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	3.2	°C/W

Notes

a. Package Limited

b. Pulse width limited by maximum junction temperature

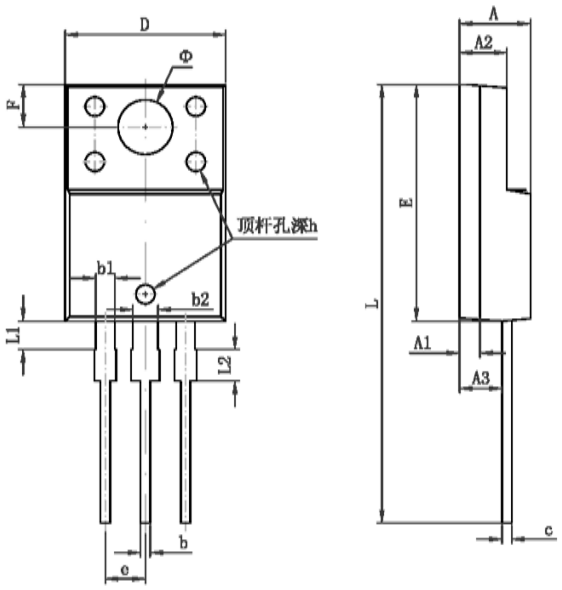
SPECIFICATIONS (T_A = 25°C UNLESS OTHERWISE NOTED)						
Parameter	**Symbol**	**Test Conditions**	**Limits**			**Unit**
			Min	**Typ**	**Max**	
Static						
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 uA	1			V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = 20 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 80 V, V_{GS} = 0 V			1	uA
		V_{DS} = 80 V, V_{GS} = 0 V, T_J = 55°C			25	
On-State Drain Current[A]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	120			A
Drain-Source On-Resistance[A]	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 2 A			16	mΩ
		V_{GS} = 5.5 V, I_D = 2 A			19	
Forward Tranconductance[A]	g_{fs}	V_{DS} = 15 V, I_D = 2 A		30		S
Diode Forward Voltage	V_{SD}	I_S = 2 A, V_{GS} = 0 V		1.1		V
Dynamic[b]						
Total Gate Charge	Q_g	V_{DS} = 15 V, V_{GS} = 5.5 V, I_D = 2 A		60		nC
Gate-Source Charge	Q_{gs}			19		
Gate-Drain Charge	Q_{gd}			39		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 25 V, R_L = 25 Ω , I_D = 2 A, V_{GEN} = 10 V		25		nS
Rise Time	t_r			49		
Turn-Off Delay Time	$t_{d(off)}$			111		
Fall-Time	t_f			44		

Notes

a. Pulse test: PW <= 300us duty cycle <= 2%.

b. Guaranteed by design, not subject to production testing.

Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.300	4.700	0.169	0.185
A1	1.300 REF		0.051 REF	
A2	2.800	3.200	0.110	0.126
A3	2.500	2.900	0.098	0.114
b	0.500	0.750	0.020	0.030
b1	1.100	1.350	0.043	0.053
b2	1.500	1.750	0.059	0.069
c	0.500	0.750	0.020	0.030
D	9.960	10.360	0.392	0.408
E	14.800	15.200	0.583	0.598
e	2.540 TYP		0.100 TYP	
F	2.700 REF		0.106 REF	
Φ	3.500 REF		0.138 REF	
h	0.000	0.300	0.000	0.012
L	28.000	28.400	1.102	1.118
L1	1.700	1.900	0.067	0.075
L2	1.900	2.100	0.075	0.083